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ABSTRACT

COMPOSITE OVERMOLDED WAFER CARRIER

A wafer carrier (20), formed from at least two different melt processable plastic materials, has a plurality of slots for holding wafers in an axially aligned configuration. The wafer carrier (20) comprises of a base portion (44) formed of a first processable plastic material and a plurality of wafer contact portions (46) including wafer seating portions overmolded on the base portion (44), the wafer contact portions (46) formed of a second processable plastic material. The wafer contact portions (46), bonded to the base portion (44), define the plurality of slots (28). A method of manufacturing an integral composite wafer carrier (20) is also defined the process comprising the steps of molding a base portion (44) of a first processable plastic material, overmolding a plurality of wafer contact portions (46) on the base portion (44) so that the wafer contact portions (46) are bonded to the base portion (44). The wafer carrier (20) is preferably a H-bar wafer carrier.

(Figure 1)